

## C1206C222F1GECTU

Aliases (C1206C222F1GEC7800)

ESD SMD Comm COG, Ceramic, 2200 pF, 1%, 100 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 1206



Click [here](#) for the 3D model.

### Dimensions

Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
T	1.1mm +/-0.10mm
B	0.5mm +/-0.25mm

### Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2500

### General Information

Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	25 mg
Shelf Life	78 Weeks
MSL	1

### Specifications

Capacitance	2200 pF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	1%
Voltage DC	100 VDC
ESD Level per AEC-Q200	16,000 V ESD Level
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms